Special Issue

Advanced Materials and Reliability for Microelectronics

Message from the Guest Editors

We invite you to submit contributions dealing with the design and fabrication of advanced materials for microelectronic applications, as well as the reliability of microelectronic devices and systems. From experimental techniques to data analysis, the scope of the Special Issue is to incorporate and combine topics such as the development and application of (1) experimental methods and methodological workflows for material research and reliability testing, (2) device technology, (3) computational modeling and simulations, as well as (4) advanced data analysis and embedded computing systems incorporating artificial intelligence (AI)-based concepts. The Special Issue shall in particular address industrial relevant research in the field of microelectronics. For further reading, please visit the ***Special Issue website.***

Guest Editors

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Deadline for manuscript submissions

closed (30 June 2022)

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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